

Title (en)

FREE-DRAINING FINNED SURFACE ARCHITECTURE FOR A HEAT EXCHANGER

Title (de)

GERIPPTE OBERFLÄCHENARCHITEKTUR MIT FREIEM ABFLUSS FÜR EINEN WÄRMETAUSCHER

Title (fr)

ARCHITECTURE À SURFACE À AILETTES AUTO-DRAINANTE POUR ÉCHANGEUR DE CHALEUR

Publication

**EP 2478318 A4 20140528 (EN)**

Application

**EP 10817599 A 20100331**

Priority

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Abstract (en)

[origin: WO2011034633A1] A free-draining heat exchanger includes a first heat exchange tube, a second heat exchange tube spaced from and generally parallel to the first heat exchange tube, and a fin contacting the first and second heat exchange tubes. The fin includes a louver and at least one drainage enhancement feature for promoting removal of liquid from external surfaces of the heat exchanger. A free-draining fin structure includes an array of fins disposed between adjacent heat exchange tubes for improving water drainage by reducing liquid surface tension. Each fin in the array includes an opening and a louver for directing airflow through the opening and around the fin and at least one drainage enhancement feature.

IPC 8 full level

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Citation (search report)

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- See references of WO 2011034633A1

Designated contracting state (EPC)

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